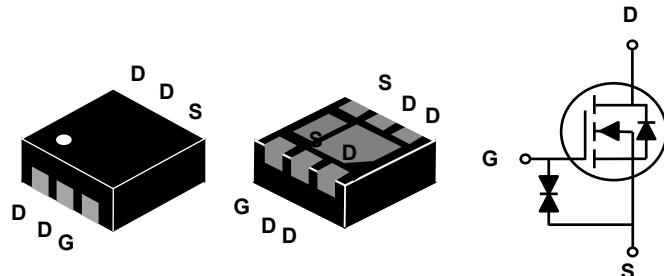


Main Product Characteristics

$V_{(BR)DSS}$	20V
$R_{DS(ON)}$	13mΩ
I_D	9.9A



Features and Benefits

DFN2x2-6L 2EP

Schematic Diagram

- Advanced MOSFET process technology
- Ideal for battery operated systems, load switching, power converters and other general purpose applications
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFB2310L utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous ($T_A=25^\circ\text{C}$)	I_D	9.9	A
Drain Current-Continuous ($T_A=70^\circ\text{C}$)		7.9	
Drain Current-Pulsed ¹	I_{DM}	39.6	A
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	2.01	W
Power Dissipation-Derated above 25°C		0.016	W/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W
Operating Junction Temperature Range	T_J	-55 To +150	°C
Storage Temperature Range	T_{STG}	-55 To +150	°C

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	-	0.02	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DS}}^{\text{SS}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{DS}}=16\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 10	μA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	-	10	13	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=3\text{A}$	-	11.5	15.5	$\text{m}\Omega$
		$V_{\text{GS}}=1.8\text{V}, I_{\text{D}}=2\text{A}$	-	15	21	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	0.3	0.6	1	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	2	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=10\text{V}, I_{\text{S}}=5\text{A}$	-	12	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q_g	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=5\text{A}, V_{\text{GS}}=4.5\text{V}$	-	16.9	26	nC
Gate-Source Charge ^{2,3}	Q_{gs}		-	1.1	3	
Gate-Drain Charge ^{2,3}	Q_{gd}		-	4	7	
Turn-On Delay Time ^{2,3}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=10\text{V}, R_{\text{G}}=25\Omega, V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1\text{A}$	-	6.8	13	nS
Rise Time ^{2,3}	t_r		-	20	38	
Turn-Off Delay Time ^{2,3}	$t_{\text{d}(\text{off})}$		-	41.8	79	
Fall Time ^{2,3}	t_f		-	13.2	25	
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	1020	1480	pF
Output Capacitance	C_{oss}		-	160	240	
Reverse Transfer Capacitance	C_{rss}		-	110	160	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	2	4	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	-	-	9.9	A
Pulsed Source Current	I_{SM}		-	-	19.8	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V

Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Pulse test: pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operation temperature.

Typical Electrical and Thermal Characteristic Curves

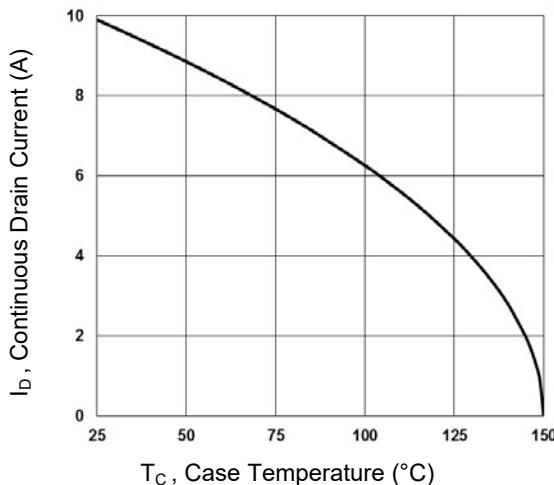


Figure 1. Continuous Drain Current vs. T_c

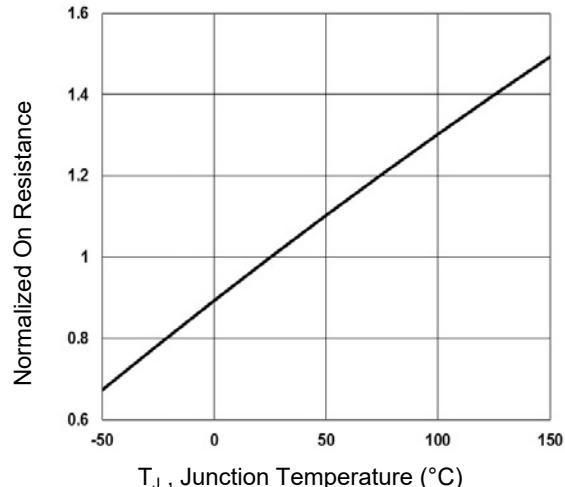


Figure 2. Normalized R_{DS(on)} vs. T_j

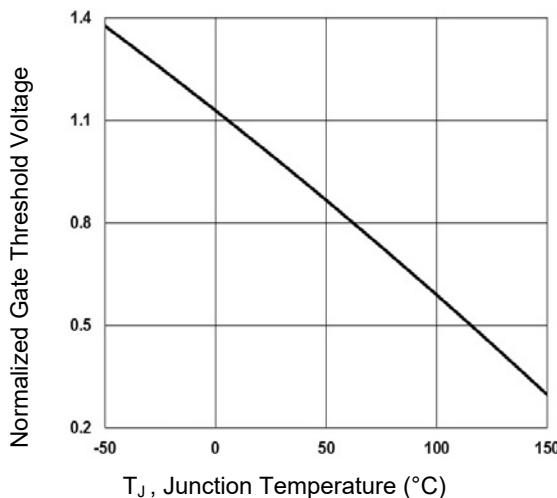


Figure 3. Normalized V_{th} vs. T_j

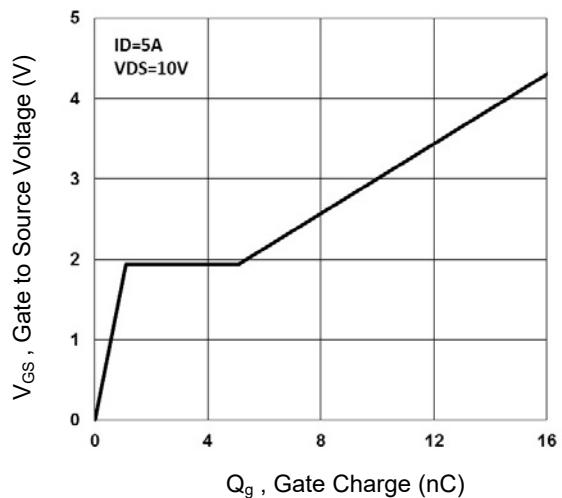


Figure 4. Gate Charge Waveform

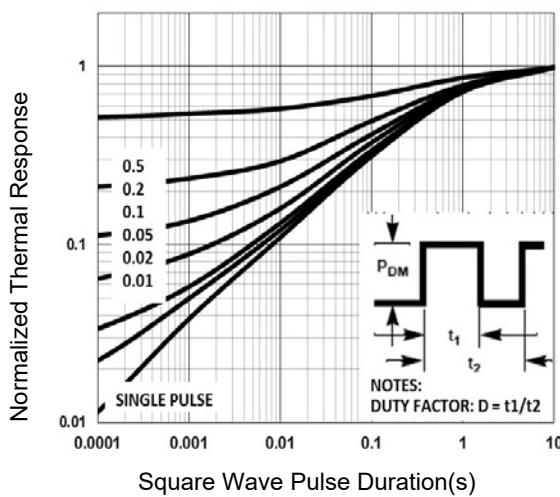


Figure 5. Normalized Transient Response

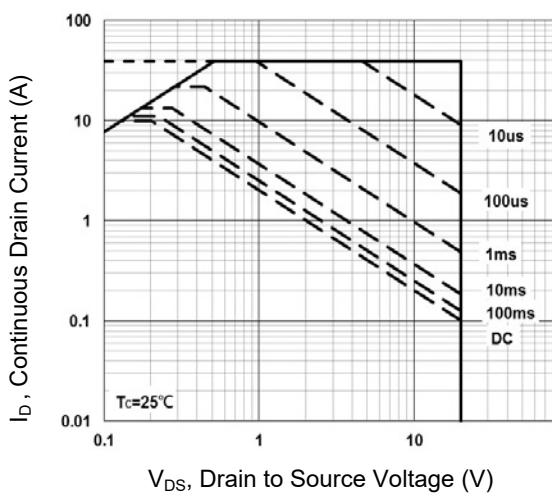


Figure 6. Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

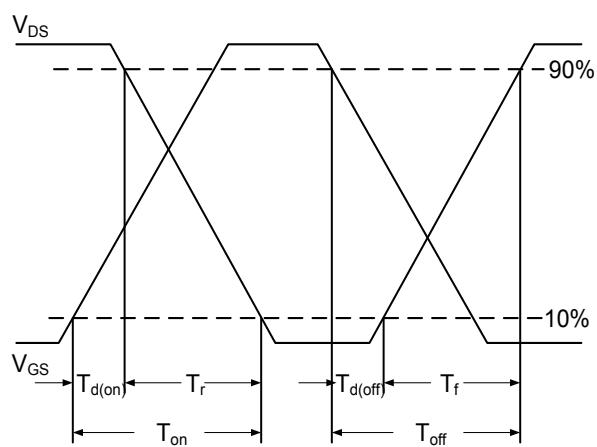


Figure 7. Switching Time Waveform

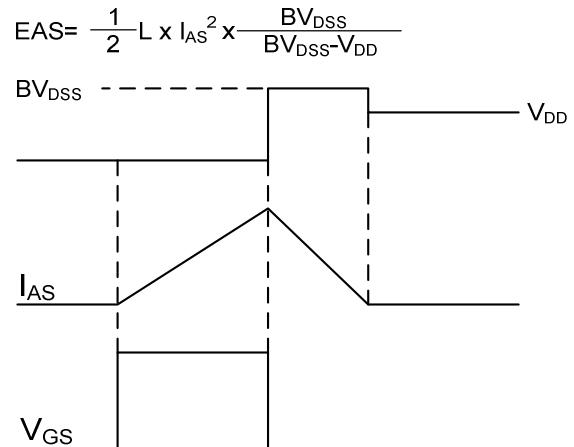
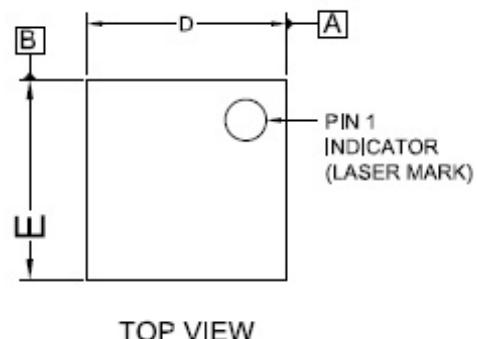
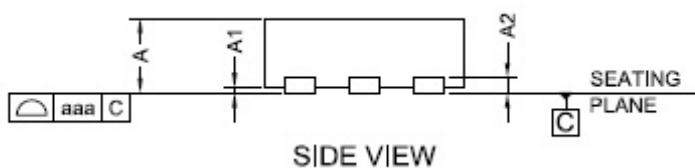
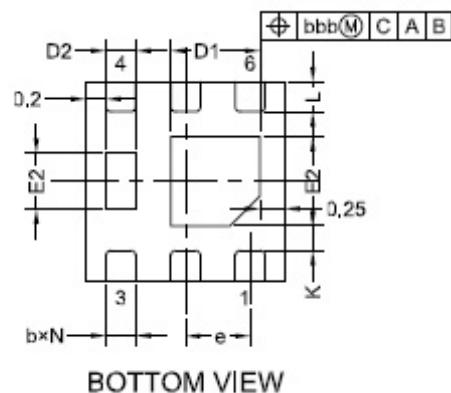


Figure 8. EAS Waveform

Package Outline Dimensions

DFN2x2-6L 2EP



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2	0.152REF		
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D1	0.80	0.90	1.00
D2	0.25	0.30	0.35
E	1.95	2.00	2.05
E1	0.80	0.90	1.00
E2	0.46	0.56	0.66
e	0.65BSC		
L	0.25	0.30	0.35
J	0.40BSC		
K	0.20MIN		
N	6.00		
aaa	0.08		
bbb	0.10		